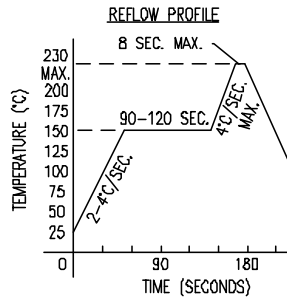
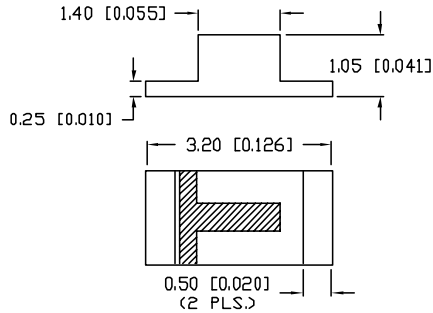
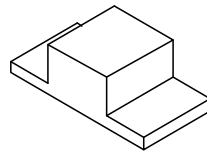
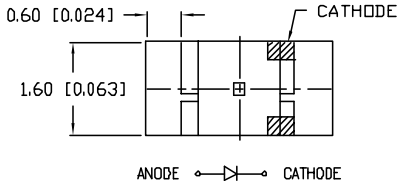


UNCONTROLLED DOCUMENT

PART NUMBER
SML-LXR1206GW-TR

REV.



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		12		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		$2x$ theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	65	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING TEMP.	-30 TO +85	$^\circ\text{C}$
STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$

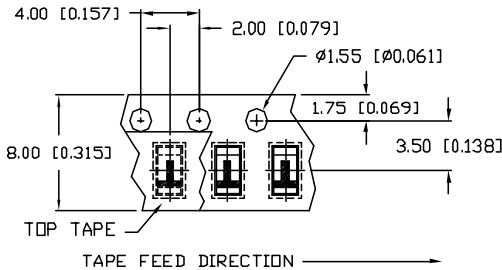
* $t < 10\mu\text{s}$

NOTES:

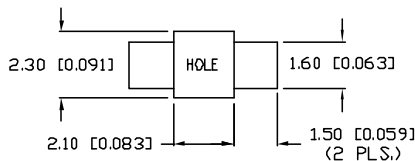
- 2,000 PIECES PER REEL.
- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE

- SHELF LIFE IN SEALED BAG:
12 MONTHS AT $<40^\circ\text{C}$ AND $<30\%$ RELATIVE HUMIDITY (RH).
- AFTER THIS BAG IS OPENED, DEVICES HAVE TO BE MOUNTED WITHIN 48 HOURS OR STORED AT $<30\%$ RH.



RECOMMENDED SOLDER PAD LAYOUT



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV.	PART NUMBER SML-LXR1206GW-TR	CONFIDENTIAL INFORMATION THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	LUMEX INCORPORATED	290 E. HELLEN ROAD PALATINE, ILLINOIS 60067 PHONE: (847) 359-2790 WEB: http://www.lumex.com
	2.0mm x 1.25mm SURFACE MOUNT LED, REVERSE MOUNT, 565nm GREEN LED, MILKY WHITE DIFFUSED, TAPE AND REEL.	RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: SS/BC	CHECKED BY: APPROVED BY: DATE: 12.20.00
				PAGE: 1 OF 1 SCALE: N/A